

# Operator-Oriented Operation for the Workplace Compact Surface Texture Measuring Instrument for Easy Operation



The customize function can be used to create a special menu where only the icons that are used most frequently are displayed, substantially enhancing operational efficiency.



# Al Function (Patented)

The AI (artificial intelligence) function automatically selects the ideal cut-off value, measuring range and other conditions simply by entering the parameters and allowable values denoted on the machining drawing. This automates measurement.

## set and the parameters to be calculated.



Measuring conditions and measured data can be stored in a PC card and read whenever necessary. This data can be output in text format and read on a personal computer. Storage of data on CF cards is also possible.

**Evaluation Range Setting (Patented)** 

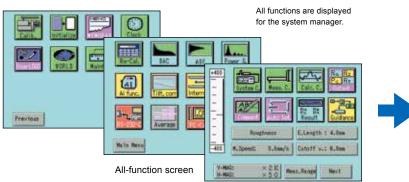
The waveform on the screen is enclosed by two

cursors, allowing the desired evaluation range to be

# ACCRETECH TOKYO SEIMITSU

# **SURFCOM 130A**

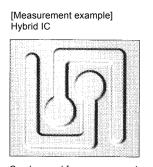
### **Convenient Mode Select Function for System Manager/Operator**



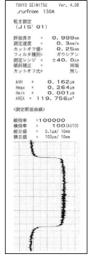
Only required functions are displayed for the operator.



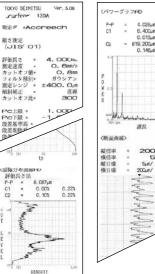
### Level difference profile evaluation function



Can be used for measurement of level difference, film thickness and area of hybrid IC, magnetic head, etc.



**Data Sheet** 



# 4. 026µm 6. 400µm 0. 013µm 19. 200µm 2000

# **Specifications**

Model		SURFCOM 130A
Measuring range	Z-axis (vertical)	800 µm (Measuring range/resolution: 800 µm/0.012 µm, 80 µm/0.001 µm, 8 µm/0.0001 µm)
	X-axis (horizontal)	50 mm
Straightness accuracy		0.3 µm/50 mm
Analysis items	Standards	Complies with JIS2013, JIS2001, JIS1994, JIS1982, ISO2009, ISO1997, ISO1984, DIN1990, ASME1995, CNOMO
	Parameters	Ra, Rq, Ry, Rp, Rv, Rc, Rz, Rmax, Rt, Rz. J, R3z, Sm, S, RΔa, RΔq, Rλa, Rλq, TILT A, Ir, Pc, Rsk, Rku, Rk, Rpk, Rvk, Mr1, Mr2, VO, K, tp, Rmr, tp2, Rmr2, Rσc, AVH, Hmax, Hmin, AREA, NCRX, R, Rx, AR, NR, CPM, SR, SAR
	Evaluation curves	Section profile curve, roughness curve, filtered waviness curve, filtered center line waviness curve, rolling circle waviness curve, rolling circle center line waviness curve, DIN4776 special curve, roughness motif curve, waviness motif curve, envelope waviness curve
	Surface characteristics graphs	Bearing area curve, amplitude distribution curve, power spectrum curve
	Tilt correction	Linear correction, round surface correction, first half correction, latter half correction, both end correction, spline curve correction (linear, round surface and both end correction possible in arbitrary range)
Magnifica- tion	Vertical (Z-axis)	50, 100, 200, 500, 1 k, 2 k, 5 k, 10 k, 20 k, 50 k, 100 k, auto
	Horizontal (X-axis)	1, 2, 5, 10, 20, 50, 100, 200, 500, 1 k, 2 k, 5 k, auto
Type of filter		Standard filter (2RC), phase compensation filter (2RC), phase compensation filter (Gaussian)
Measuring speed		0.3, 0.6, 1.5, 3 mm/s (4 speeds)
Detector		Tip radius: 2 µm, Material: Diamond, Measuring force: 0.75 mN
Special functions	AI function	Al function provide for easy procedures, enabling beginners to conduct measurements.
	Level difference analysis function	Ideal for film thickness and surface area measurement of semiconductor parts.
	PC card	Data output as text file for transfer to a personal computer.
Standard accessories		Reference specimen (E-MC-S24C), recording paper (E-CH-S21A), touch pen (E-MA-S54A), operation manual, support ware
Dimensions and weight	Power supply, frequency, consumption	AC 100 V to 240 V ±10%, 50 Hz/60 Hz, 30 VA
	Installation dimensions (W x D x H)	700 mm × 300 mm × 150 mm
	Weight	8 kg

\*The correspondence to the special specification of measuring pressure power or stylus is also possible.

